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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10015757	FILING DATE 12/17/2001	CLASS 257	SUBCLASS	GAU 2811	EXAMINER Lewis
**APPLICANTS: Kim Hyung-Jun;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: REPUBLIC OF KOREA 2000-80891 12/22/2000					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO P67358US0	
Verified and Acknowledged Examiners's initials					
TITLE: Semiconductor device capable of preventing corrosion of metal wires from CMP (chemical mechanical polishing) process					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Prepared for Issue	
		Application Examiner	
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